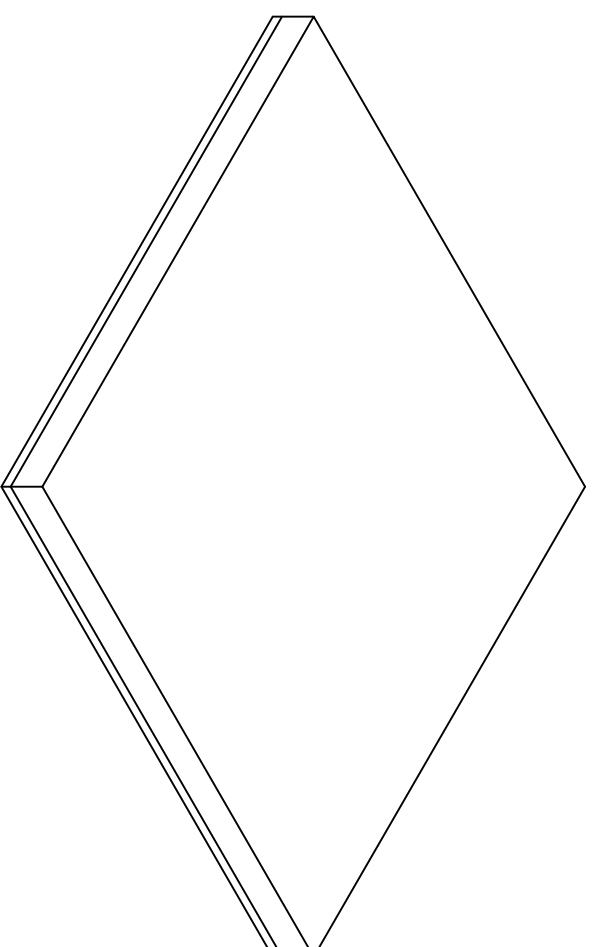


REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	C06099	INITIAL RELEASE	MCM	EB	05/06/99
01	C9341	INITIAL RELEASE	SMHAN	SMHAN	07/06/00
02	C17641	CHANGE TITLE AND UPDATE FORMATS	DSHER	DSHER	08/07/02
03	NA	ADDED SHEET 4 AND 196 BGA BALL MATRIX	JGJAN	JGJAN	06/05/03
04	N/A	CORRECTED TOTAL THICK. TO 1.11 +0.09/-0.10	HOCHOI	-----	03/04/04



7. REFERENCE SPECIFICATIONS:
 A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 196.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 14 X 14.
2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Anchor Technology, Inc. Chandler, Arizona, USA Anam Semiconductor, Inc., Seoul, Korea Anchor Technology Philippines, Inc. Manila, Philippines	
DECIMAL X.X ±0.1	ANGULAR ±1°			Amkor / ANAM Semiconductor	
X.XXX ±0.05		APPROVALS	DATE	PACKAGE OUTLINE - MAF, 14 X 14 MATRIX, 12.00mm X 12.00mm X 1.11mm, 0.60mm MOLD CAP, 0.40mm BALL, 0.80mm PITCH, LAMINATE SUBSTRATE, AWW	
X.XXX ±0.030		DESIGNED SMHAN	06/05/00	STRIP DWG NUMBER/REV	N/A
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		CHECKED DARN0	06/05/00	PKG OUTLINE DWG NO.	N/A
		PRODUCT MANAGER TPANC	06/05/00	SCALE	NONE
MATERIAL N/A		RELEASED ROLM	06/06/00	DWG NUMBER	75443
FINISH N/A				SHEET	1 OF 4
DO NOT SCALE DRAWING				REV	04